

## CLAIMS

1. A field effect transistor comprising:  
a substrate comprising a source region and a  
drain region;
- 5           an insulating layer arranged on the substrate;  
and  
a porous body which has pillar-shaped holes  
arranged on the insulating layer, wherein the porous  
body includes a semiconductor material.
- 10          2. A field-effect transistor, characterized by  
comprising a porous film, which has pillar-shaped  
pores almost perpendicular to a substrate, through an  
insulating layer on a substrate, wherein the porous  
film is formed by removing a pillar-shaped material
- 15          from a structure that the pillar-shaped material  
constituted with including a first component  
disperses in a member constituted with including a  
second component which can form a eutectic with the  
first component.
- 20          3. The field-effect transistor according to  
claim 2, characterized in that the porous film is  
composed of an insulating material or a semiconductor  
material.
- 25          4. The field-effect transistor according to  
claim 3, characterized in that the semiconductor  
material is a material which uses silicon, germanium,  
or silicon and germanium as a main component.

5. The field-effect transistor according to  
claim 3, characterized in that the insulating  
material is a material which uses silicon oxide as a  
main component.

5       6. The field-effect transistor according to  
claim 1, characterized in that average pore diameter  
of the pillar-shaped pores is 20 nm or less, and mean  
pore density is  $1.5 \times 10^{11}$  pores/cm<sup>2</sup> or more.

10     7. The field-effect transistor according to  
claim 1, having on surfaces of the pillar-shaped  
pores a detected material for detecting a specific  
detection material.

15     8. The field-effect transistor according to  
claim 7, characterized in that the detection material  
is a biomaterial.

9. The field-effect transistor according to  
claim 6, characterized in that the detection material  
causes a change of an electric charge state by  
contacting with a detected material.

20     10. A sensor using the field-effect transistor  
according to claim 1.

11. A method for producing a sensor using a  
field-effect transistor, characterized by including:  
a step of preparing a structure comprising  
25     plenty of pillar-shaped members almost perpendicular  
         to a substrate, and a structural member enclosing  
         these pillar-shaped members;

a step of removing the pillar-shaped members to form pillar-shaped pores in the structural member; and

5 a step of annealing a porous film made of the structural member in which the pillar-shaped pores are formed.